



Bonding order

1/ ESD protection wires : bond first pad 8, then 91*, then 196**

* After 91, bonding possible on pads 86 to 90 (Change request 26 July 2022)

** Just before 196, bonding possible on pads 197

2/ GND wires (including IREF – see table)

3/ Other wires

Pulltest pads: 153 to 162

ChipID pads: 43, 44

ITkPix – IREF bonding reference table

